What is claimed is:

[Claim 1] 1. An integrated circuit structure comprising:

an insulator layer;

a pad comprising a conductive material on said insulator layer, said pad having a wirebond connection region and a probe pad region; and

an inspection mark between said wirebond connection region and said probe pad region,

wherein said inspection mark comprises an opening in said insulator layer that is filled with said conductive material.

[Claim 2] 2. The structure in claim 1, further comprising a polyimide layer above said conductive material, said polyimide having a second opening, wherein said pad is exposed through said second opening.

[Claim 3] 3. The structure in claim 1, wherein said inspection mark opening is formed above an insulating region of said wiring layer.

[Claim 4] 4. The structure in claim 1, wherein said conductor comprises a refractory metal.

[Claim 5] 5. The structure in claim 1, wherein said conductor comprises one of aluminum, tantalum, titanium, and alloys thereof.

[Claim 6] 6. The structure in claim 1, wherein said inspection mark is visible from an exterior of said integrated circuit structure.

[Claim 7] 7. The structure in claim 1, wherein said inspection mark delineates where probe inspection marks are permitted on said pad.

[Claim 8] 8. An integrated circuit structure comprising:

a wiring layer below said insulator layer said wiring layer comprising a conductor wire;

an insulator layer on said wiring layer;

a pad comprising a conductive material on said insulator layer, said pad having a wirebond connection region and a probe pad region;

an inspection mark between said wirebond connection region and said probe pad region, wherein said inspection mark comprises an opening in said insulator layer that is filled with said conductive material; and

a contact through said insulator layer, said contact being adapted to electrically connect said conductor wire in said wiring layer to said pad,

wherein said contact comprises said conductive material.

[Claim 9] 9. The structure in claim 8, further comprising a polyimide layer above said conductive material, said polyimide having a second opening, wherein said pad is exposed through said second opening.

[Claim 10] 10. The structure in claim 8, wherein said inspection mark opening is formed above an insulating region of said wiring layer.

[Claim 11] 11. The structure in claim 8, wherein said conductor comprises a refractory metal.

[Claim 12] 12. The structure in claim 8, wherein said conductor comprises one of aluminum, tantalum, titanium, and alloys thereof.

[Claim 13] 13. The structure in claim 8, wherein said inspection mark is visible from an exterior of said integrated circuit structure.

[Claim 14] 14. The structure in claim 8, wherein said inspection mark delineates where probe inspection marks are permitted on said pad.

[Claim 15] 15. A method of creating an inspection mark between a wirebond connection region and a probe pad region of a pad, said method comprising:

forming an insulator layer over a wiring layer;

simultaneously patterning a wiring contact opening and an inspection mark opening in said insulator layer; and

depositing a conductor material over said insulator layer such that said conductor material fills said wiring contact opening and said inspection mark opening and forms said pad on said insulator layer,

wherein said conductor material within said inspection mark opening forms said inspection mark that is between said wirebond connection region and said probe pad region.

[Claim 16] 16. The method in claim 15, further comprising:

forming a polyimide layer above said conductive material; and

forming a second opening in said polyimide layer, wherein said pad is exposed through said second opening.

[Claim 17] 17. The method in claim 15, wherein said inspection mark opening is formed above an insulating region of said wiring layer.

[Claim 18] 18. The method in claim 15, wherein said conductor comprises a refractory metal.

[Claim 19] 19. The method in claim 15, wherein said conductor comprises one of aluminum, tantalum, titanium, and alloys thereof.

[Claim 20] 20. The method in claim 15, wherein said inspection mark delineates where probe inspection marks are permitted on said pad.